



Printed Circuit Boards  
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

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# PRINTED CIRCUIT BOARDS

01

4.11.2001

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## Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 167 FR4 100 L71.100 P18\_10

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_167\_FR4\_100\_L71.100\_p18\_10

Layers	in $\mu$	Material	Build-Up	Assembly	
Layer-1	100 $\mu$	Copper			
	100 $\mu$	Prepreg			(100 $\mu$ PrePreg-Type: 2125)
	180 $\mu$	Prepreg			(180 $\mu$ PrePreg-Type: 7628)
Layer-2	100 $\mu$	Copper			
	710 $\mu$	L-FR4			
Layer-3	100 $\mu$	Copper			
	180 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
Layer-99	100 $\mu$	Copper			

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